

GLC Detector

presented by: Hitoshi Yamamoto
(Tohoku University)

Cornell, July 2003

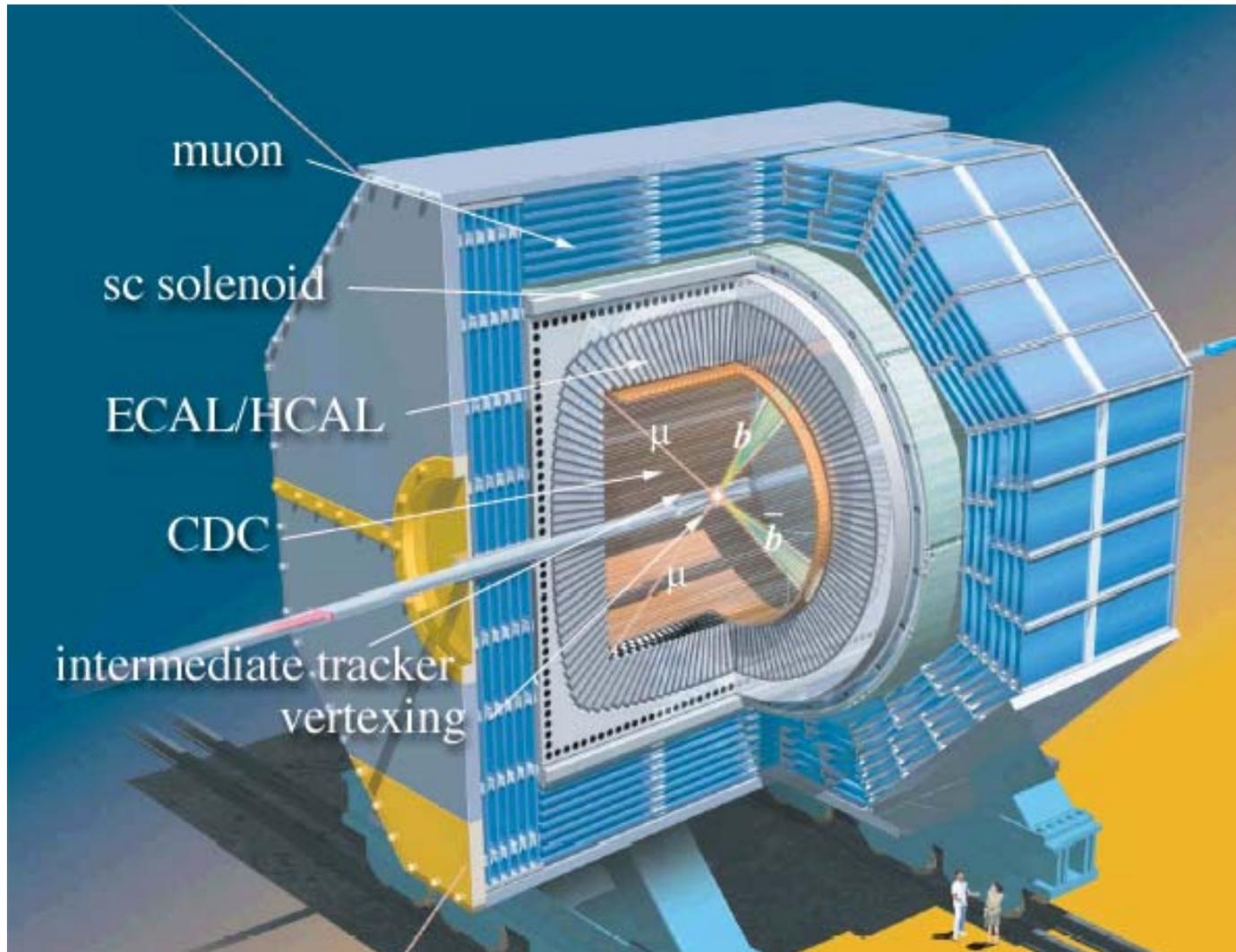
JLC: New names were solicited over internet
(EPOC, ILIAD, TYPHOON etc. etc.)

Naming committee of ACFA (chair: Prof. Namkung)
2003 May: officially renamed **JLC** → **GLC**

GLC machine parameters

version	‘A’	‘Y’
E_{CM}	535 GeV	501 GeV
pulse rep. rate	150 Hz	
#bunch/pulse	95	190
bunch separation	2.8 ns	1.4 ns
pulse duration	266 ns	
pulse to pulse	6.67 ms	
#particle/bunch	0.75×10^{10}	0.70×10^{10}
σ_x	277 nm	239 nm
σ_y	3.39 nm	2.55 nm
σ_z	90 μm	80 μm
full crossing angle	6~8 mrad	
Luminosity	$9.84 \times 10^{33}/\text{cm}^2\text{s}$	$27.0 \times 10^{33}/\text{cm}^2\text{s}$

Generic GLC detector



Evolution of GLC Detector Pradigm

Driven mostly by the solenoid field and the final focus design

- Solenoid field:

Keeps the pair backgrounds tightly around the beamline.

2 Tesla → 3 Tesla

Shrinks the size of CDC

(→ the whole detector shrinks)

- Short final focus design:

(by Raimondi&Seryi)

Final focus section 1800 → 500m ($E_b = 500$ GeV)

IP-QC1 distance (ℓ^*): 2m → 4.3m

Changes the IR design (easier in general)

Simulation

Generation of pair background:

CAIN

Ebeam=250GeV

"A" option ("Y" option)

Detector Simulation:

JIM (based on GEANT3)

Ecut for γ : 10 keV

Ecut for n: 1 keV

B field of compensation mag. & QC included

2T Detector

CDC (CO₂-IsoC₄H₁₀)

~2 hits/BX by γ

~30 hits/BX by n

230cm

VTX ($r_{\min}=2.4\text{cm}$)

W Mask ($r_{\min}=4.5\text{cm}$ at $z=30\text{cm}$)

40 cm

200 mrad

150 mrad

LUM

Compensation Mag.

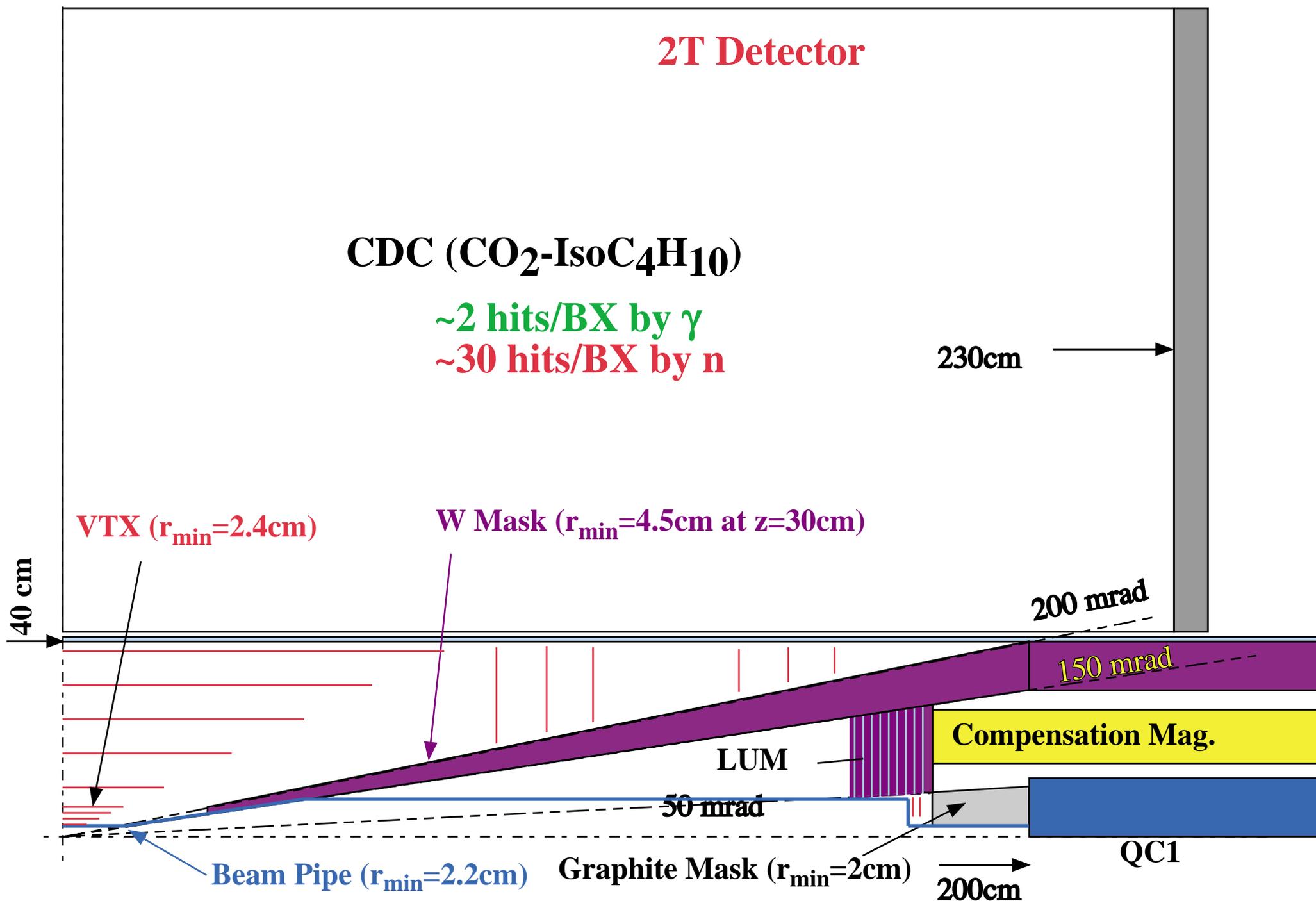
50 mrad

Beam Pipe ($r_{\min}=2.2\text{cm}$)

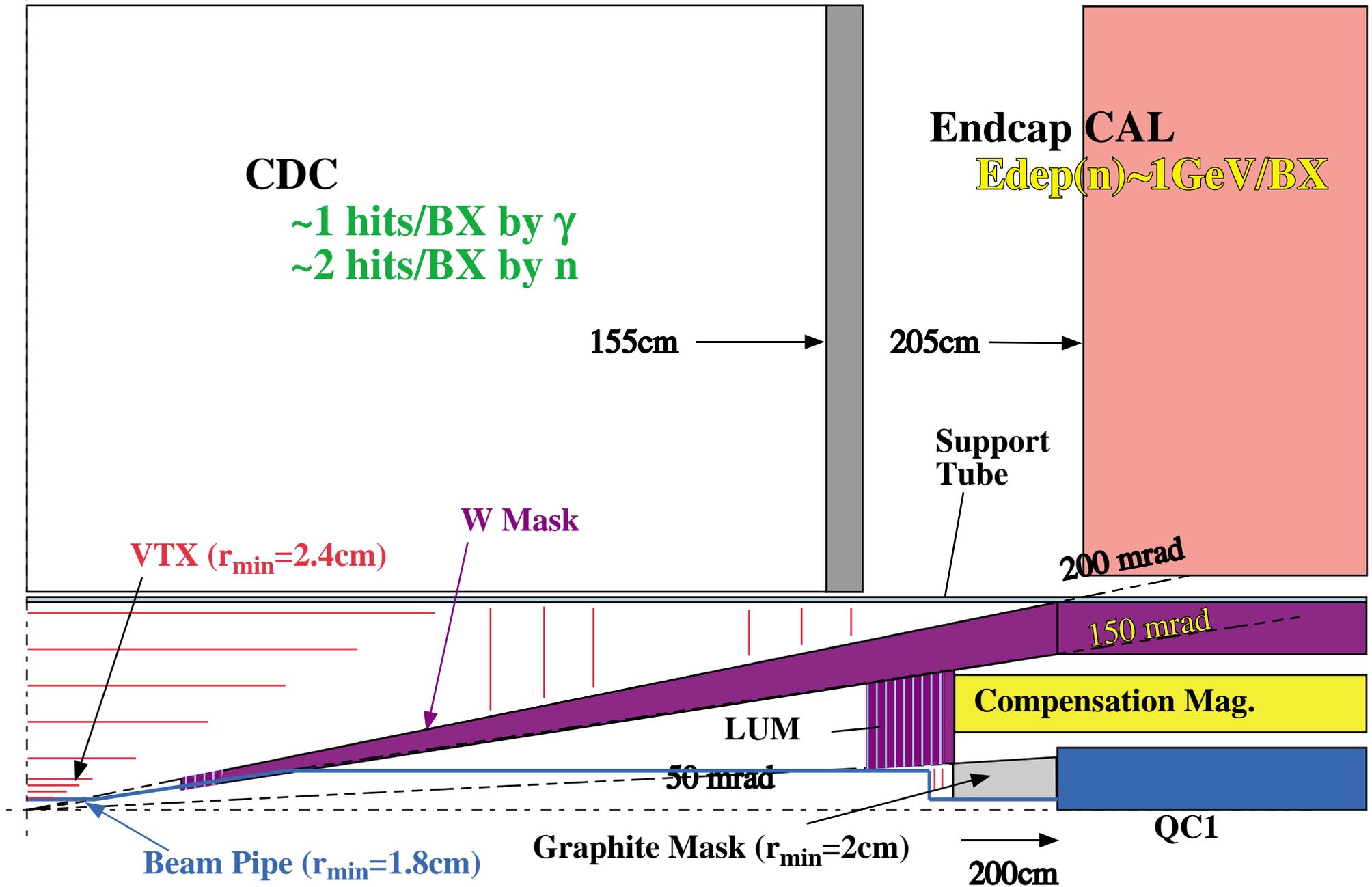
Graphite Mask ($r_{\min}=2\text{cm}$)

200cm

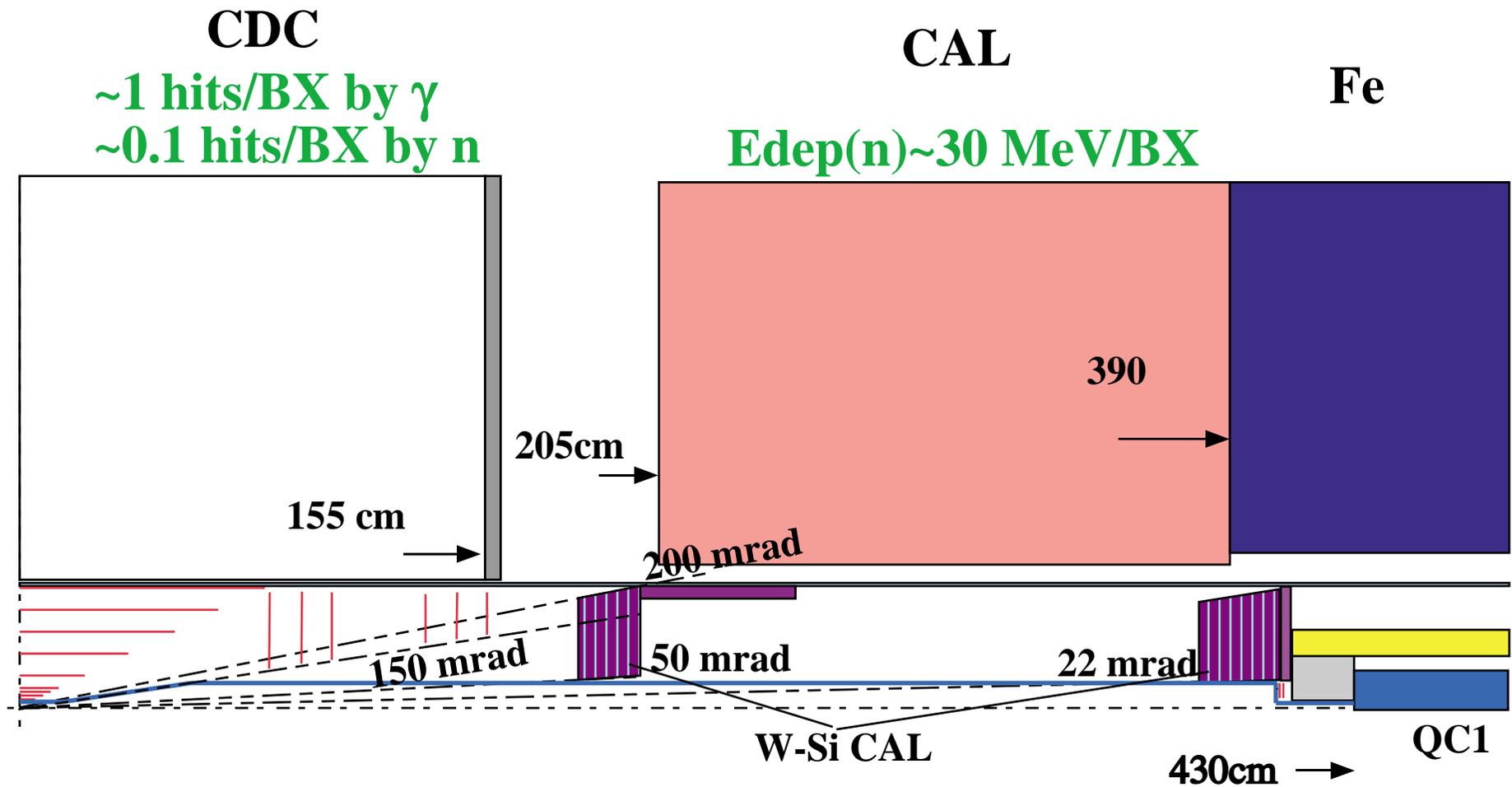
QC1



3T Detector



3T $l^*=4.3\text{m}$ Detector



Impact of the new optics ($l^*=4.3\text{m}$) on the detector

- Huge W-mask NOT needed
- Background hit much smaller (CDC, CAL)
- No need for Compensation magnet (?)
 - if the B field @4.3m is weak enough
 - or Super conducting QC1 is adopted
- Better forward coverage for calorimetry
- Smaller R_{\min} of CDC and CAL possible

Detector Model	CDC hits / BX		CAL Edep (GeV / BX)		θ_{\min} (mrad)
	(γ)	(n)	(γ)	(n)	
2T	2	30	~0	0.6	50
3T ($l^*=2\text{ m}$)	1	2	~0	0.9	50
3T ($l^*=4.3\text{ m}$)	1	0.1	0.01	0.03	22

Vertex Detector

Present Design Parameters in JIM (JLC full Simulator)

- 4 layers of CCDs at $r = 24, 36, 48, 60$ mm
-- Another layer at smaller r ?

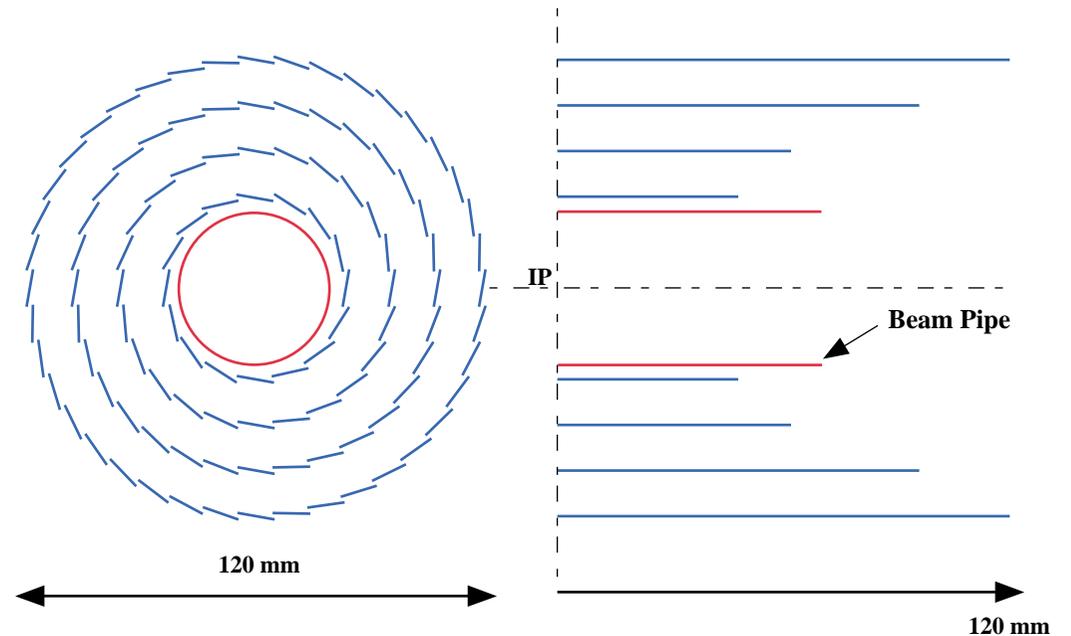
- Angular coverage of $|\cos\theta| < 0.9$

- Wafer thickness of $300 \mu\text{m}$
-- Thinner wafer ?

- Pixel size of $25 \mu\text{m}^2$

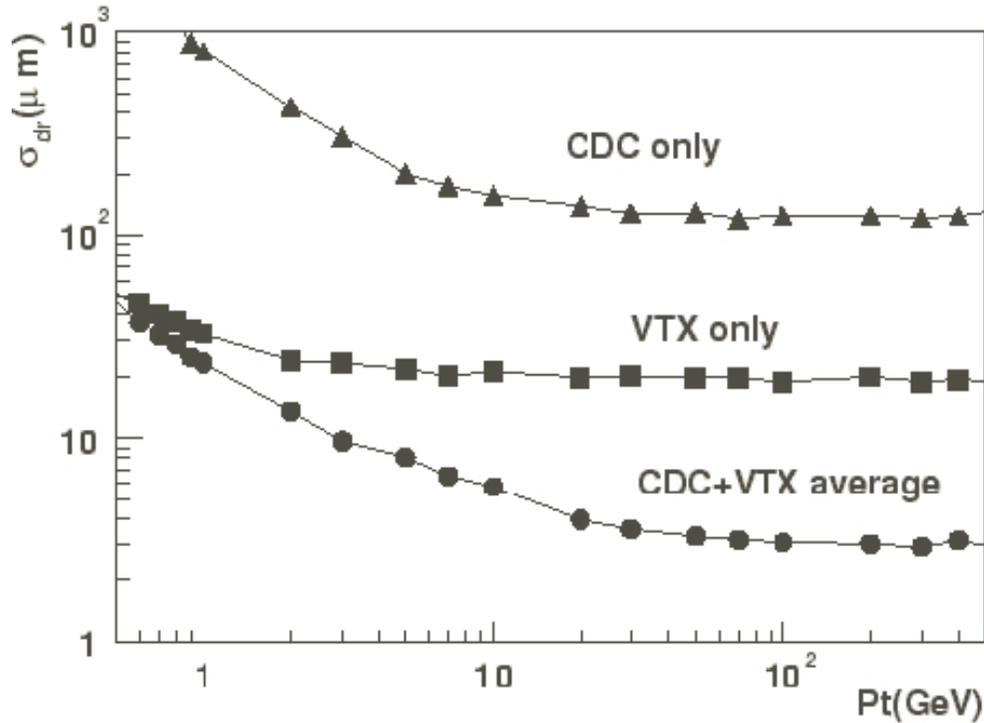
- $\sigma = 4 \mu\text{m}$

- $\delta^2 = 7^2 + (20/p)^2 / \sin^3\theta$ [μm]

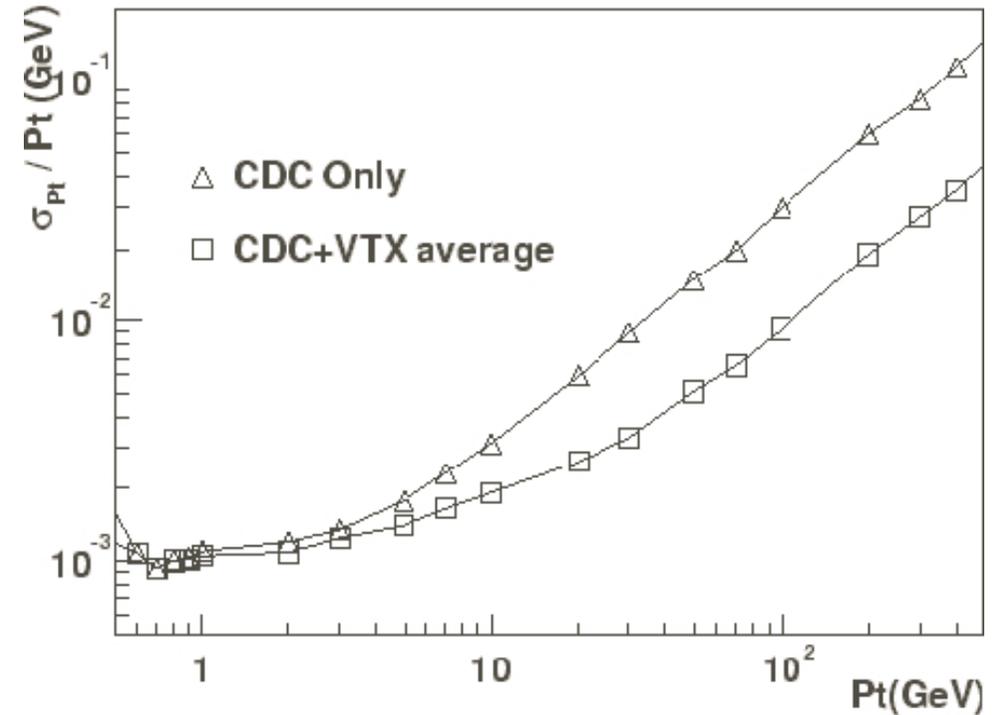


Expected Performance of CCD Vertex Detector

Impact parameter (2D) resolution



Momentum resolution



Better than $7\mu\text{m}$ expected by VTX alone at large Pt due to high resolution CDC

$$\sigma_b = \frac{\sigma_{in} r_{out}}{r_{out} - r_{in}} \oplus \frac{\sigma_{out} r_{in}}{r_{out} - r_{in}} \oplus \frac{0.014 r_{in}}{p\beta} \sqrt{\frac{Xr}{\sin^3\theta}}$$

R&D Status & Plan of CCD Vertex Detector

1) Spatial resolution

- Resolution of $<3\mu\text{m}$ has been confirmed with test beam
- Laser beam (1064 nm) scanner with $2\mu\text{m}$ spot size (Niigata Univ.)

2) Study of distortion of CCD wafers

Thinner wafer is desirable

--- $20\mu\text{m}$ is enough for particle detection

--- but how to support?

Thermal distortion should be reasonably small
and has repeatability

Idea of C.Damerell's group: $50\mu\text{m}$ wafer stretched from both ends

-> proposed in TESLA TDR

Another idea: Partially thinned wafer like SHOJI in traditional Japanese house

System of distortion measurement has been constructed

3) CCD radiation hardness

The result of our study so far using ^{90}Sr irradiation is;

CCD can survive > 3 years with

B = 2T

Rmin = 24 mm

Machine parameter "A" (Standard Luminosity)

But it is preferable to have

Rmin < 24 mm

High Luminosity ("Y") Option

-> Study of radiation hardness should be continued

Issues to be studied:

- Effect of readout speed

-> Fast readout (~10MHz) is needed

- How to inject the "Fat Zero Charge"

- Radiation damage effect on the spatial resolution

-> @Niigata Univ.

- Radiation damage by high energy (>10MeV) electrons

-> Sooner or later

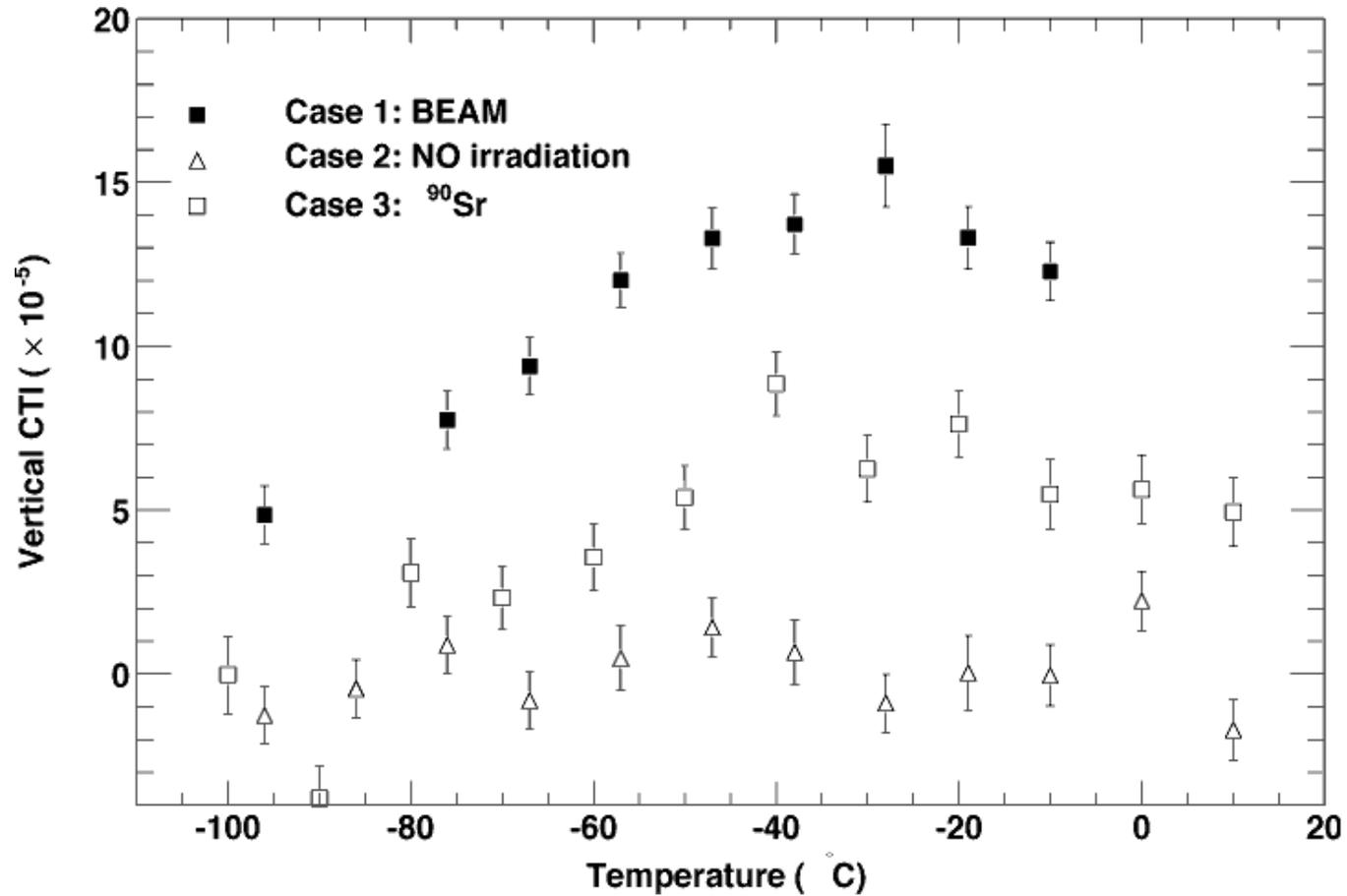
4) Fast readout electronics

CCD Signal Processor chip for Digi-Cam

- Correlated double sampler**
- Variable gain amp**
- 10bit/40MHz or 12bit/20MHz ADC**

These functions in 9x9 mm² chip size by \$6/chip

Vertical CTI



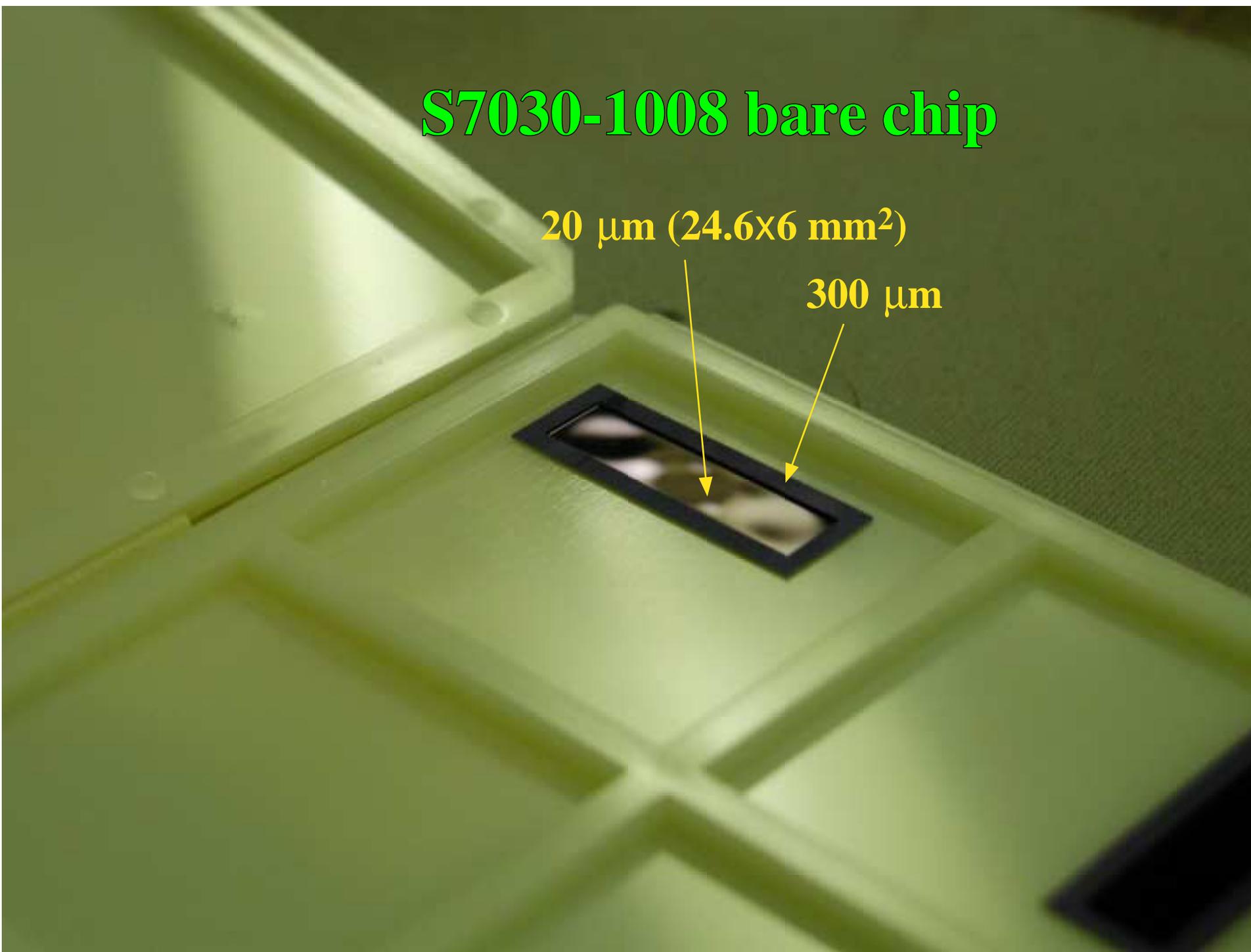
(Beam = 150 MeV electrons. Sr90/beam both $6 \times 10^{10}/\text{cm}^2$.)



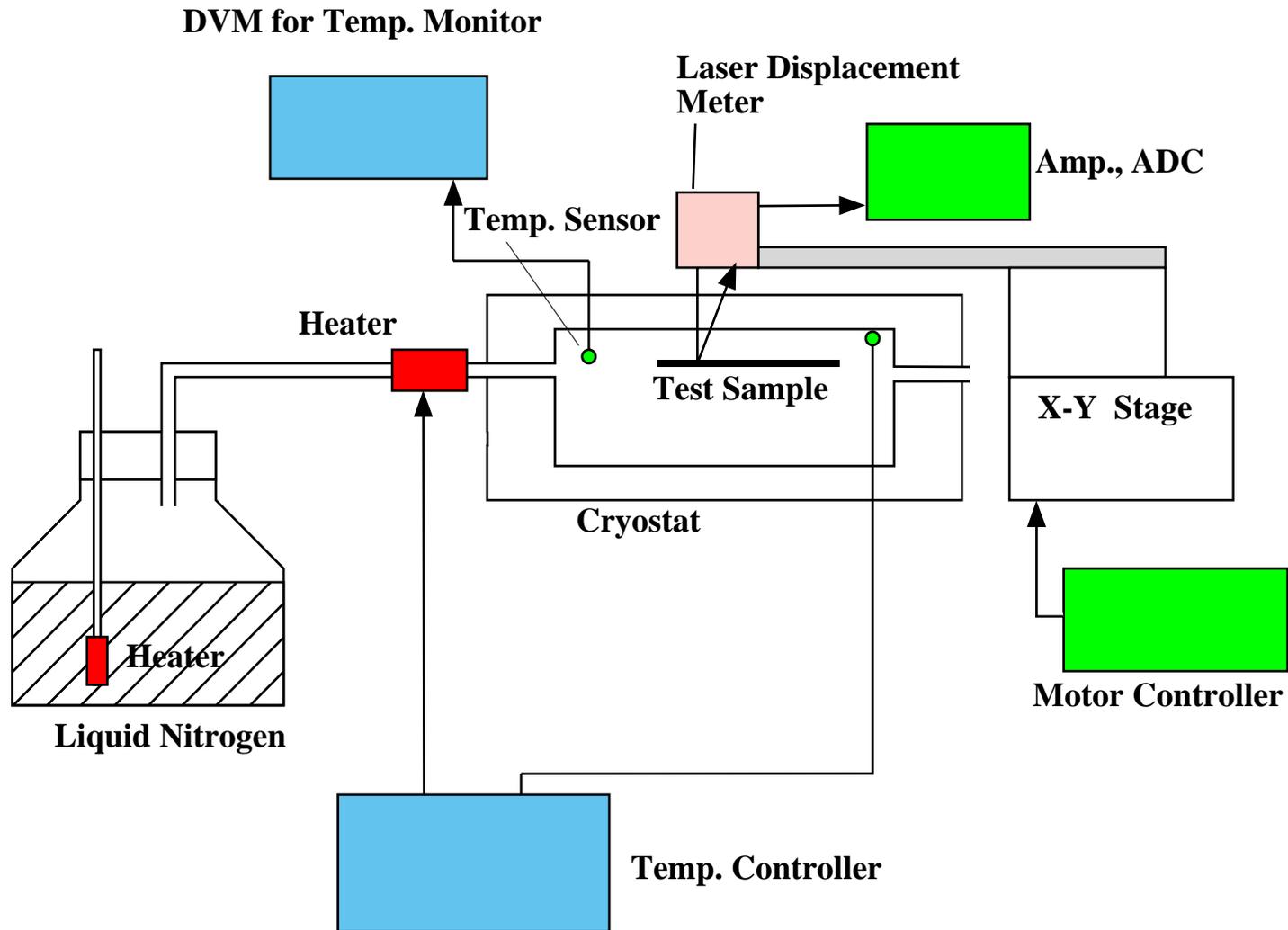
S7030-1008 bare chip

20 μm (24.6x6 mm²)

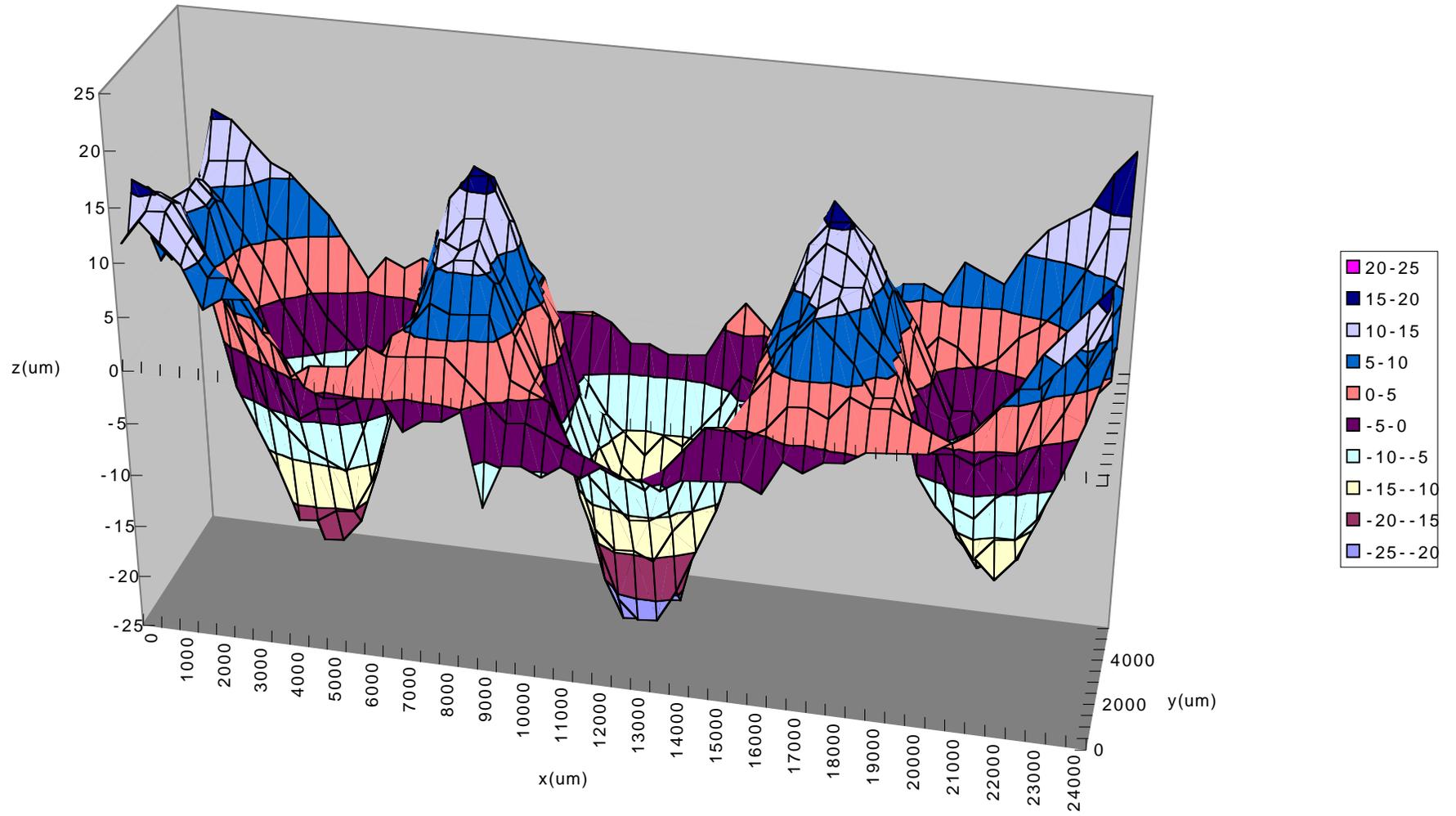
300 μm

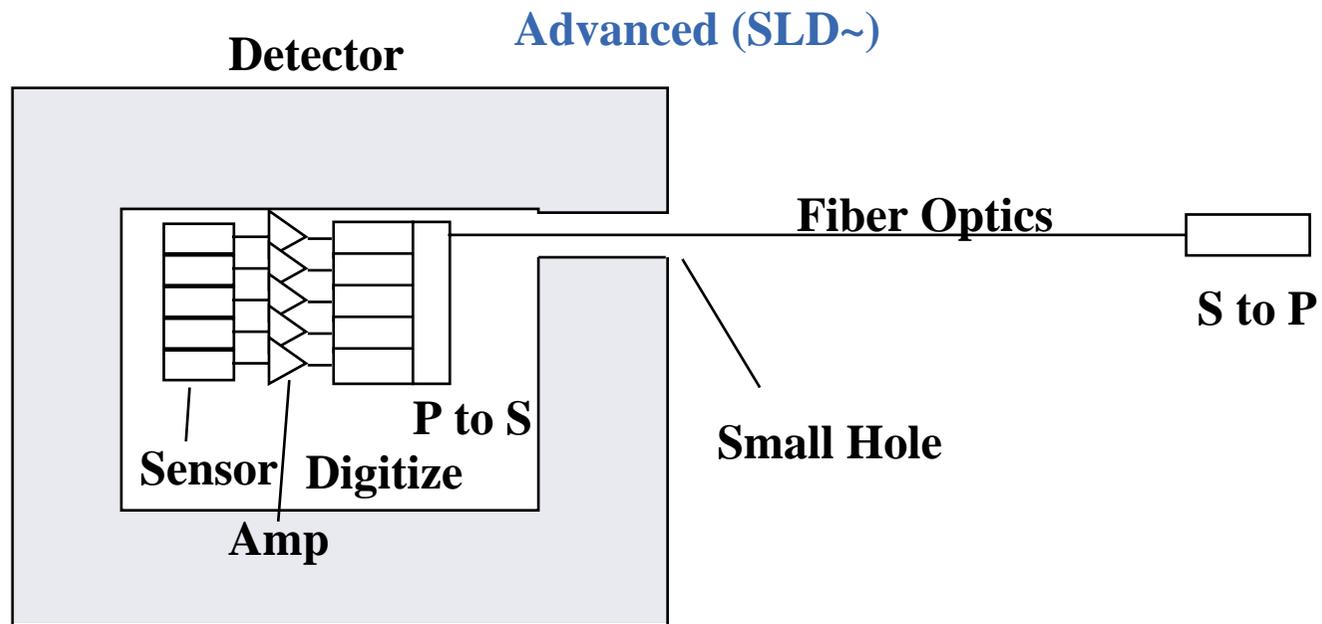
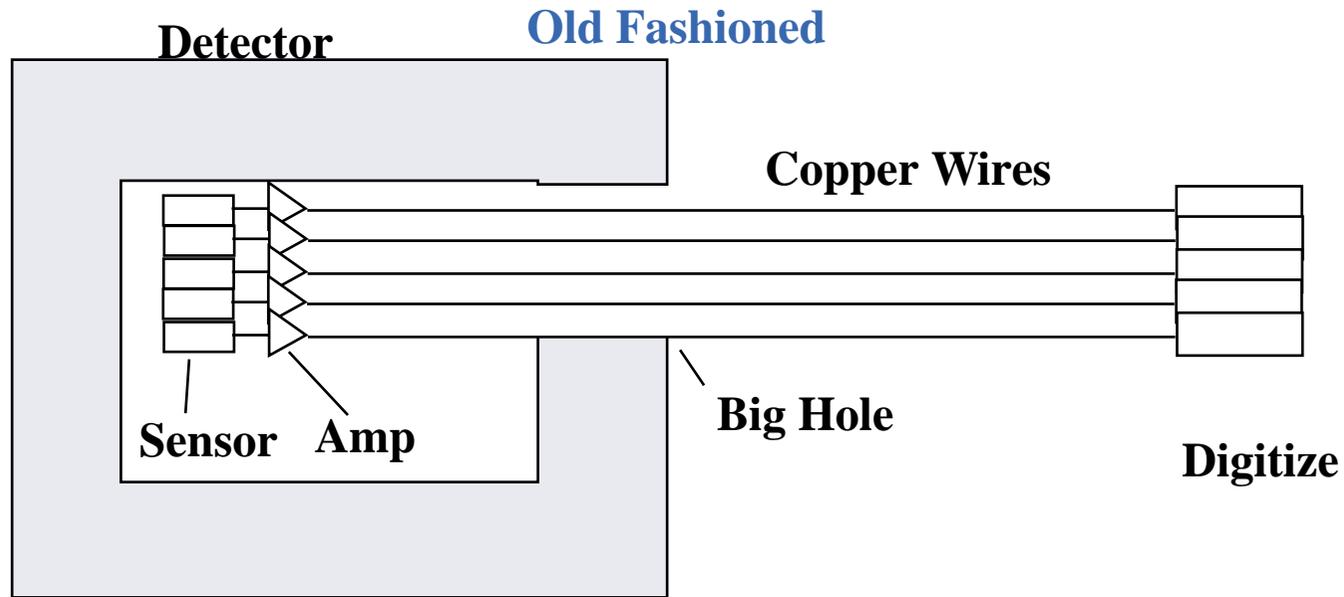


Measurement System



S7030 (27deg)





	SLD (VTX3)	JLC
# of pixels	307 M	> 320 M
Readout time	200 ms	6 ms
R.O. frequency	5 MHz	20 (40) MHz
# of r.o. ch	384	> 2600 (1300)
Throughput	15 Gbps	> 500 Gbps
Fiber Optics	960Mbps x 16	3.4 Gbps (IEEE1394b) x 150 ??

Current CDC Parameters (R&D)

Mini-jet cell structure (5 anode wires /cell)

Gas mixture CO_2 (90%) – C_4H_{10} (10%)

$$\sigma_{xy} = 85 \mu\text{m}$$

2-Tesla option

$$R_{\text{in}} = 45 \text{ cm}$$

$$R_{\text{out}} = 230 \text{ cm}$$

$L = 460 \text{ cm}$ (Length of the chamber)

$$B = 2 \text{ T}$$

$n = 80$ (Number of sampling points)

3-Tesla option

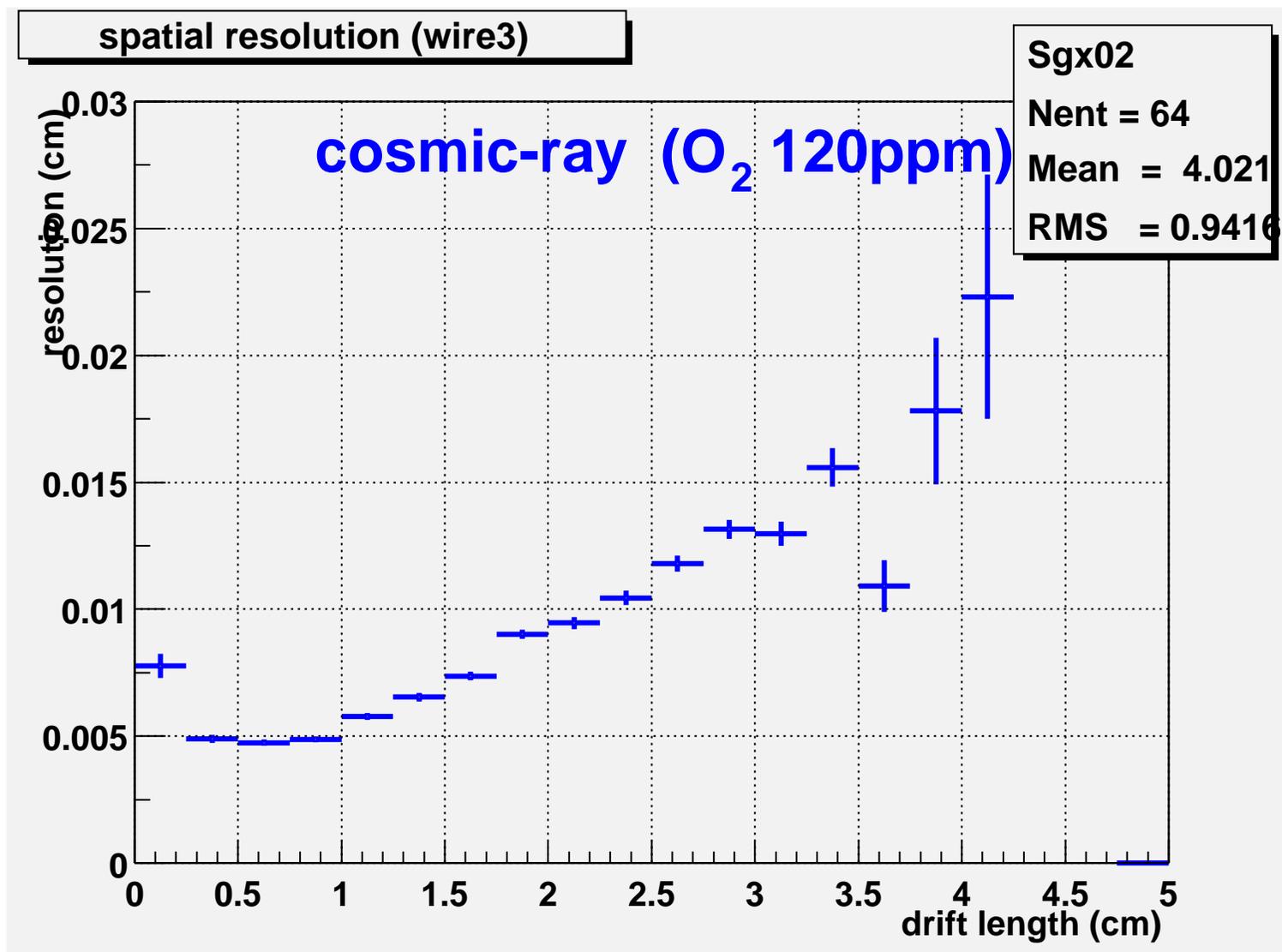
$$R_{\text{in}} = 45 \text{ cm}$$

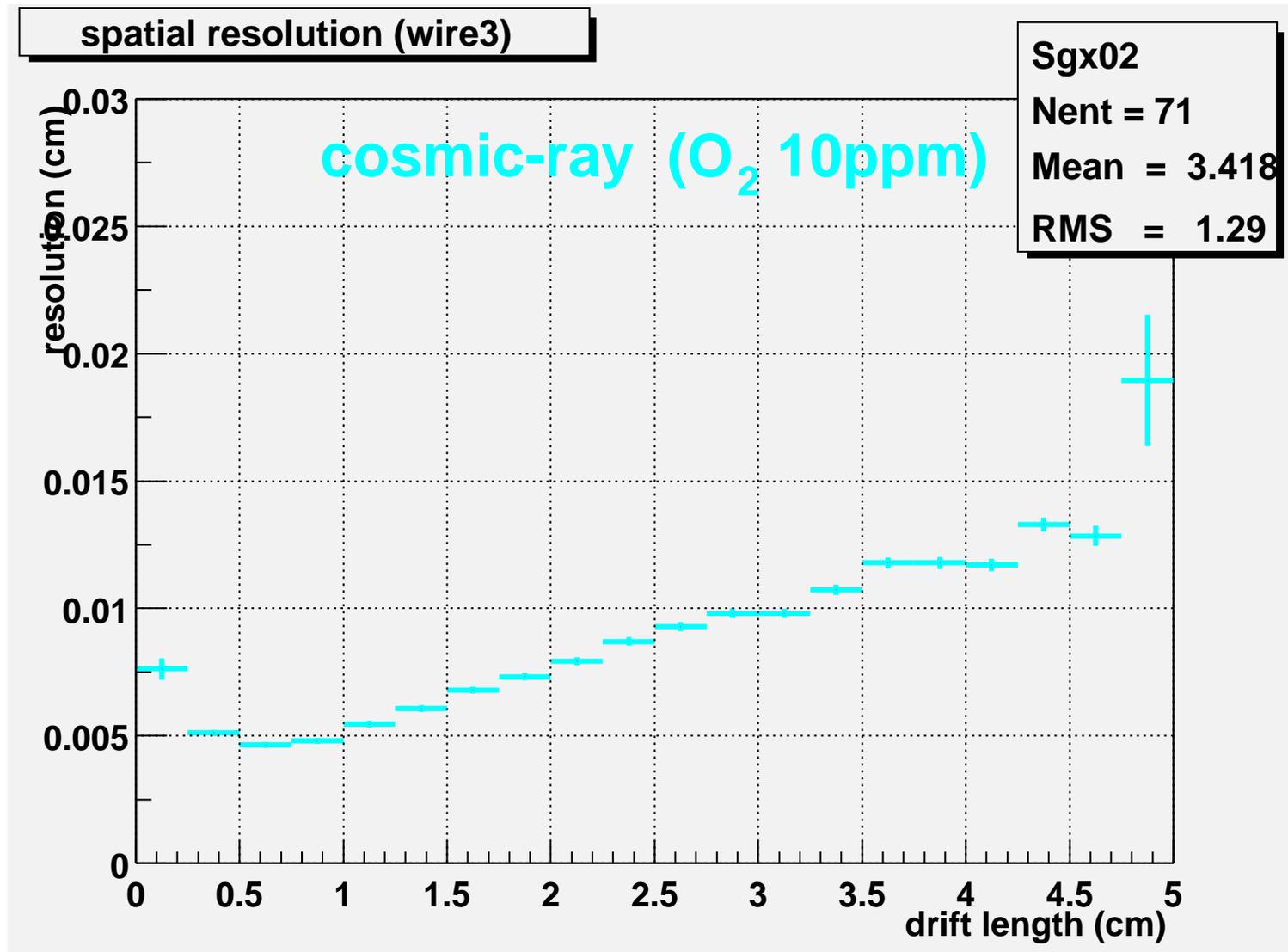
$$R_{\text{out}} = 155 \text{ cm}$$

$L = 310 \text{ cm}$ (Length of the chamber)

$$B = 3 \text{ T}$$

$n = 50$ (Number of sampling points)





Calorimeter

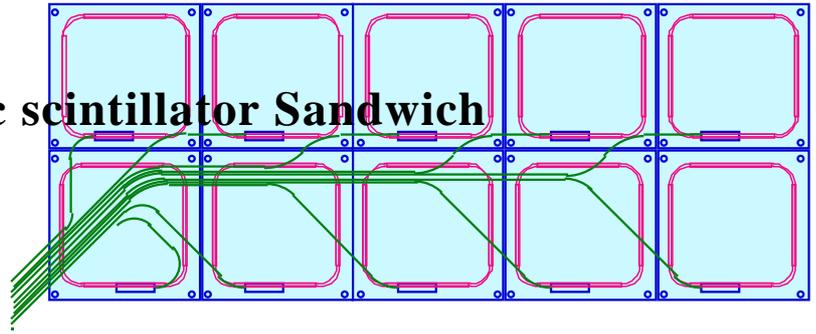
Baseline Design

- **Structure : Lead/Plastic scintillator Sandwich**

EM : Pb/Sci=4mm/1mm

had : Pb/Sci=8mm/2mm

- **Scheme : Tile/Fiber**



with hardware compensation

- **Granularity : as small as reasonably achievable...under study**

Baseline Rect-Tile

EM : 4cm x 4cm (24mrad) x 3 longitudinal samplings

had : 14cmx14cm (72mrad) x 4 longitudinal samplings

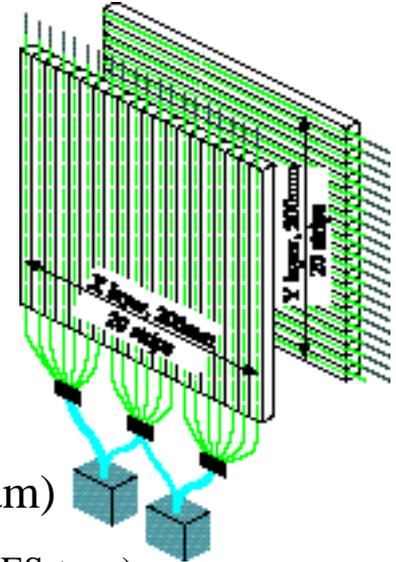
Strip-EM option

1cm-wide strip-array (x-y layers) x ~20 longitudinal samplings

- Shower Max Detector

Baseline : 1cm-wide strip-array (x-y layers)

Option : 1cm x 1cm Si-pad



Performances

- Single-particle response (measured with testbeam)

$E/E = 15.4\% / E + 0.2\%$ for electrons (ZUES-type)

$E/E = 46.7\% / E + 0.9\%$ for pions

$x = 2\sim 3\text{mm}$ even at over 50GeV

pion rejection = 1/1400 at $\epsilon = 98\%$

- **Jet response : under simulation study**

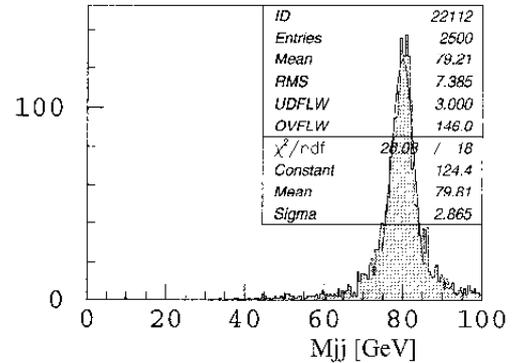
Recent Activities

[I] Granularity Optimization with Full Simulation

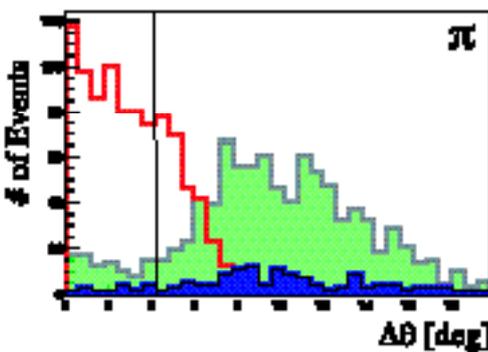
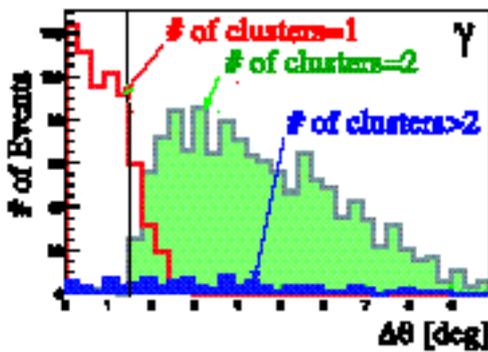
Analysis of quick-simulation data gives very good performance
... but it is not the end of the story.

1) Construction of full-simulator

- Done for baseline design (Rect-Tile).
- not yet for optional design (strip-EM).



2) Shower clustering ; in progress but very difficult



- a) hadron shower clustering
- 2D-JADE ; not successful yet
 - 2D-contiguous ; not successful yet
 - 3D-contiguous ; not successful yet
 - **Super-cluster = French method not yet tried (below)**

- b) decomposition of overlapping showers under study including its necessity itself
- c) track-cluster association under study including 1st principle ; whether **one-to-one** or **plural-to-one**

Algorithm

- Geometrical approach
- First step: link together all hits within a certain angle and distance

The diagram shows a cone with a dashed vertical axis. A horizontal line across the cone is labeled ϵ_1 . A point on the cone's surface is labeled α_1 . Three stars (two blue, one red) are placed on the cone's surface, representing hits.

- Second step: find baricenter and direction for each cluster and link together clusters within a certain angle and distance
- Four geometrical parameters (two distances and two angles)

Coming R&D plans

1) Further full-simulation studies on granularity optimization

2) Beam tests of fine-granularity EM module

includes

- Strip-EMC
- Rect-Tile EMC
- Direct-readout SHmax
- Optimum photon detectors for each

3) Lead alloy and structures

- Further studies on alloys and hybrid materials
Make test pieces of SUS-Pb sandwich
- Engineering studies on structure

4) Mass production of tiles and fiber assemblies

- Tiles ; Design optimization for "moldable" tiles
MEGA-tile structure, groove cross section, etc.
- Fiber assemblies ; low-cost heat-splicing, mirroring, etc.

Summary/Concluding Remarks

1. The name change: JLC → GLC
2. New an longer IR seems promising, but details needs to be studied.
3. Steady progresses on each front, but holes exist:
Forward tracker, Intermediate tracker, particle ID.
4. Other options need to be studied: TPC, digital calorimeter.
5. Still more efforts needed for jet reconstruction study.